



CY74FCT16244T
CY74FCT162244T
CY74FCT162H244T

Output Drive Characteristics for CY74FCT16244T

Parameter	Description	Test Conditions	Min.	Typ. ^[5]	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-3 mA	2.5	3.5		V
		V _{CC} =Min., I _{OH} =-15 mA	2.4	3.5		V
		V _{CC} =Min., I _{OH} =-32 mA	2.0	3.0		V
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =64 mA		0.2	0.55	V

Output Drive Characteristics for CY74FCT162244T, CY74FCT162H244T

Parameter	Description	Test Conditions	Min.	Typ. ^[5]	Max.	Unit
I _{ODL}	Output LOW Current ^[8]	V _{CC} =5V, V _{IN} =V _{IH} or V _{IL} , V _{OUT} =1.5V	60	115	150	mA
I _{ODH}	Output HIGH Current ^[8]	V _{CC} =5V, V _{IN} =V _{IH} or V _{IL} , V _{OUT} =1.5V	-60	-115	-150	mA
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-24 mA	2.4	3.3		V
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =24 mA		0.3	0.55	V

Notes:

5. Typical values are at V_{CC}=5.0V, T_A = +25°C ambient.
6. This parameter is specified but not tested.
7. Pins with bus hold are described in Pin Description.
8. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
9. Tested at +25°C.



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Capacitance^[6]($T_A = +25^\circ\text{C}$, $f = 1.0 \text{ MHz}$)

Parameter	Description	Test Conditions	Typ. ^[5]	Max.	Unit
C_{IN}	Input Capacitance	$V_{IN} = 0\text{V}$	4.5	6.0	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0\text{V}$	5.5	8.0	pF

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ. ^[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	$V_{CC}=\text{Max.}$	$V_{IN} \leq 0.2\text{V}, V_{IN} \leq V_{CC}-0.2\text{V}$	5	500 μA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	$V_{CC}=\text{Max.}$	$V_{IN}=3.4\text{V}^{[10]}$	0.5	1.5 mA
I_{CCD}	Dynamic Power Supply Current ^[11]	$V_{CC}=\text{Max.}, \text{One Input Toggling, 50\% Duty Cycle, Outputs Open, } \overline{OE}=\text{GND}$	$V_{IN}=V_{CC} \text{ or } V_{IN}=\text{GND}$	60	100 $\mu\text{A/MHz}$
I_C	Total Power Supply Current ^[12]	$V_{CC}=\text{Max.}, f_1=10 \text{ MHz, 50\% Duty Cycle, Outputs Open, One Bit Toggling, } \overline{OE}=\text{GND}$	$V_{IN}=V_{CC} \text{ or } V_{IN}=\text{GND}$	0.6	1.5 mA
			$V_{IN}=3.4\text{V} \text{ or } V_{IN}=\text{GND}$	0.9	2.3 mA
		$V_{CC}=\text{Max.}, f_1=2.5 \text{ MHz, 50\% Duty Cycle, Outputs Open, Sixteen Bits Toggling, } \overline{OE}=\text{GND}$	$V_{IN}=V_{CC} \text{ or } V_{IN}=\text{GND}$	2.4	$4.5^{[13]}$ mA
			$V_{IN}=3.4\text{V} \text{ or } V_{IN}=\text{GND}$	6.4	$16.5^{[13]}$ mA

Notes:

10. Per TTL driven input ($V_{IN} = 3.4\text{V}$); all other inputs at V_{CC} or GND.
 11. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
 12. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 - $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_1/2 + f_1 N_1)$
 - I_{CC} = Quiescent Current with CMOS input levels
 - I_{CC} = Power Supply Current for a TTL HIGH input ($V_{IN}=3.4\text{V}$)
 - D_H = Duty Cycle for TTL inputs HIGH
 - N_T = Number of TTL inputs at D_H
 - I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
 - f_0 = Clock frequency for registered devices, otherwise zero
 - f_1 = Input signal frequency
 - N_1 = Number of inputs changing at f_1
- All currents are in millamps and all frequencies are in megahertz.

13. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.



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Switching Characteristics Over the Operating Range^[14]

Parameter	Description	CY74FCT16244T CY74FCT162244T		CY74FCT16244AT CY74FCT162244AT CY74FCT162H244AT		Unit	Fig. No. ^[15]
		Min.	Max.	Min.	Max.		
t _{PLH} t _{PHL}	Propagation Delay Data to Output	1.5	6.5	1.5	4.8	ns	1, 3
t _{PZH} t _{PZL}	Output Enable Time	1.5	8.0	1.5	6.2	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time	1.5	7.0	1.5	5.6	ns	1, 7, 8
t _{SK(O)}	Output Skew ^[16]		0.5		0.5	ns	—

Switching Characteristics Over the Operating Range^[14] (continued)

Parameter	Description	CY74FCT16244CT CY74FCT162244CT CY74FCT162H244CT		CY74FCT16244ET CY74FCT162244ET CY74FCT162H244ET		Unit	Fig. No. ^[15]
		Min.	Max.	Min.	Max.		
t _{PLH} t _{PHL}	Propagation Delay Data to Output	1.5	4.1	1.5	3.2	ns	1, 3
t _{PZH} t _{PZL}	Output Enable Time	1.5	5.8	1.5	4.4	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time	1.5	5.2	1.5	3.6	ns	1, 7, 8
t _{SK(O)}	Output Skew ^[16]		0.5		0.5	ns	—

Notes:

14. Minimum limits are specified but not tested on Propagation Delays.

15. See "Parameter Measurement Information" in the General Information section.

16. Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.



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Ordering Information CY74FCT16244

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.2	CY74FCT16244ETPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT16244ETPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
4.1	CY74FCT16244CTPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT16244CTPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
4.8	CY74FCT16244ATPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT16244ATPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
6.5	CY74FCT16244TPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT16244TPVC/PVCT	O48	48-Lead (300-Mil) SSOP	

Ordering Information CY74FCT162244

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.2	74FCT162244ETPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162244ETPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT162244ETPVC	O48	48-Lead (300-Mil) SSOP	
4.1	74FCT162244CTPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162244CTPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT162244CTPVC	O48	48-Lead (300-Mil) SSOP	
4.8	74FCT162244ATPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162244ATPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT162244ATPVC	O48	48-Lead (300-Mil) SSOP	
6.5	CY74FCT162244TPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162244TPVC/PVCT	O48	48-Lead (300-Mil) SSOP	

Ordering Information CY74FCT162H244

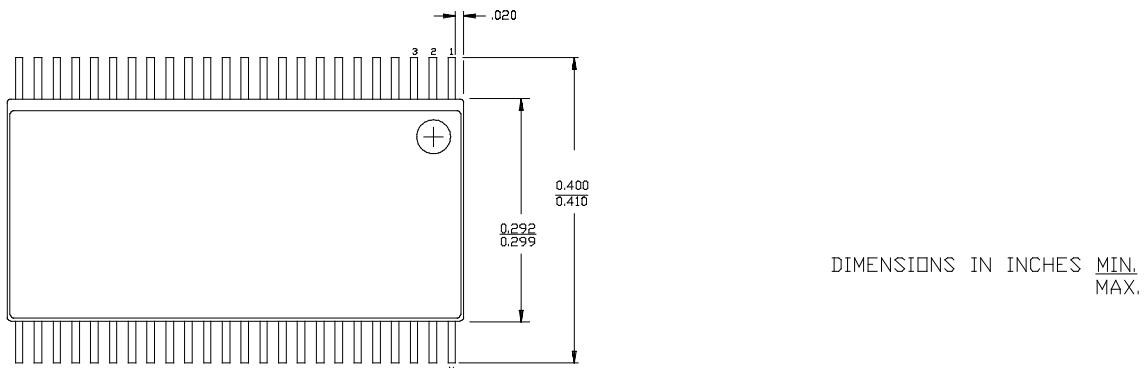
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.2	74FCT162H244ETPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	74FCT162H244ETPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
4.1	74FCT162H244CTPVC/PVCT	O48	48-Lead (300-Mil) SSOP	Industrial
4.8	74FCT162H244ATPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial



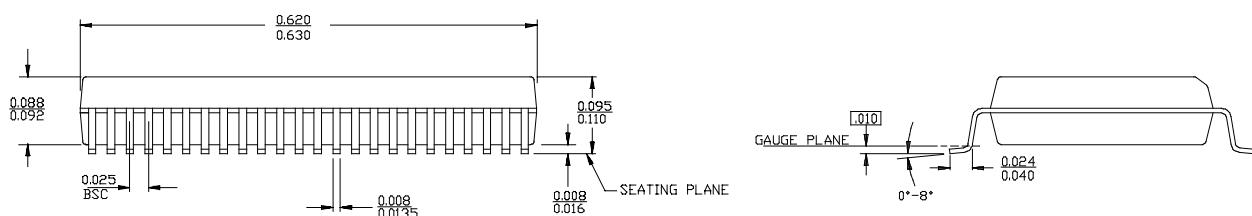
**CY74FCT16244T
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Package Diagrams

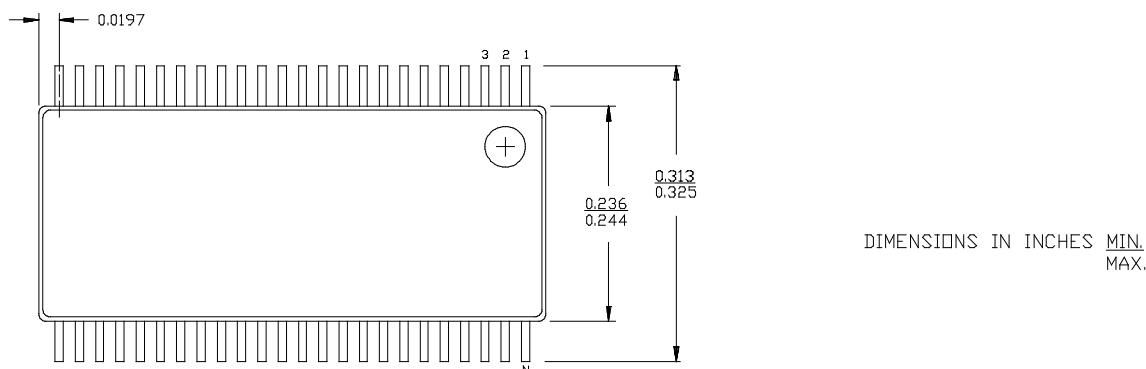
48-Lead Shrunk Small Outline Package O48



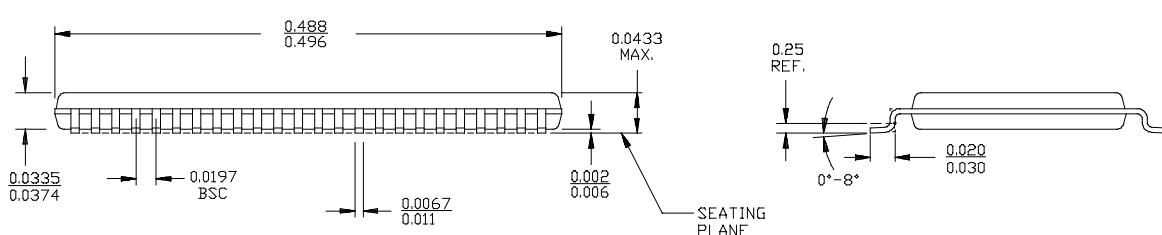
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48-Lead Thin Shrunk Small Outline Package Z48



DIMENSIONS IN INCHES MIN.
MAX.



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